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Journal of MATERIALS RESEARCH

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Cover: Electron backscatter diffraction (EBSD) mappings of solder joints subjected to multiple solder reflows. [Y. Wang, K.H. Lu, V. Gupta, L. Stiborek, D. Shirley, S-H. Chae, J. Im, and P.S. Ho: Effects of Sn grain structure on the electromigration of Sn–Ag solder joints. p. 1131.]

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- 1198–1204 **A Q-DLTS investigation of aluminum nitride surface termination** Jason B. Rothenberger, Daniel E. Montenegro, Mark A. Prelas, Tushar K. Ghosh, Robert V. Tompson, Sudarshan K. Loyalka

COMMENTS AND REPLY

Commentary

- 1205–1207 **Comment to paper “Penetration depth and tip radius dependence on the correction factor in nanoindentation measurements” by J.M. Meza et al. [J. Mater. Res. 23(3), 725 (2008)]** Karsten Durst, Hamad ur Rehman, Benoit Merle

Reply

- 1208–1210 **A response to—“Comment on the evaluation of the constant β relating the contact stiffness to the contact area in nanoindentation for spheroc-conical indenters:” Comment to paper “Penetration depth and tip radius dependence on the correction factor in nanoindentation measurements” by J.M. Meza et al. [J. Mater. Res. 23(3), 725 (2008)]** Juan Manuel Meza, Fazilay Abbes, Jaime Alexis Garcia Guzman, Michel Troyon